



MJ P-Channel Enhancement Mode Power MOSFET

Description

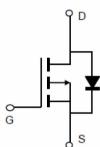
The MJ30P16Q uses advanced trench technology to provide excellent RDS(ON), low gate charge. This device is suitable for use as a load switch or in PWM applications.

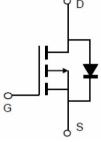
General Features

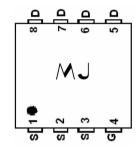
- ♦ V_{DS}=-30V.I_D=-16A $R_{DS(ON)}$ <30m Ω @ V_{GS} =-4.5V $R_{DS(ON)}$ <18m Ω @ Vgs=-10V
- High Power and current handing capability
- ◆ Lead free product is acquired
- Surface mount package

Application

- ▶ PWM applications
- Load switch
- Power management







Schematic diagram

Marking and pin assignment

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ30P16Q	MJ30P16Q	DFN3.3X3.3	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (Tc =25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	-16	Α
Drain Current-Continuous(Tc =100°C)	I _{D(100°C)}	-11.3	А
Drain Current-Pulsed (Note 1)	Ірм	-64	А
Maximum Power Dissipation	Po	30	W
Operating Junction and Storage Temperature Range	ТJ ,Тsтg	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	RөJA	4.2	°C/W
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Electrical Characteristics (T_A =25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =-250µA	-30	-	-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =-30V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	Vos=Vgs ,Io=-250µA	-1.2	-1.6	-2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	Vgs=-10V, ID=-10A	-	13	18	mΩ
Dialii-Source Oil-State Resistance	Rds(ON)	V _{GS} =-4.5V, I _D =-10A	-	22	30	mΩ
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-10A	-	20	-	S
Dynamic Characteristics (Note 4)					I	
Input Capacitance	Clss		-	1363	-	PF
Output Capacitance	Coss	V _{DS} =-15V,V _{GS} =0V, F=1.0MHz	-	250	-	PF
Reverse Transfer Capacitance	Crss		-	210	-	PF
Switching Characteristics (Note 4)				1		
Turn-on Delay Time	td(on)		-	9	-	nS
Turn-on Rise Time	tr	Vdd=-30V, Rl=3Ω,	-	10	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =-10V,R _G =2.5Ω	-	25	_	nS
Turn-Off Fall Time	tr		-	10	-	nS
Total Gate Charge	Qg		-	31.2	-	nC
Gate-Source Charge	Qgs	V _{DS} =-15V,I _D =-10A, V _{GS} =-10V	-	3.2	_	nC
Gate-Drain Charge	Q _{gd}		-	9.2	_	nC
Drain-Source Diode Characteristics					<u> </u>	
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =-10A	-		-1.2	V
Diode Forward Current (Note 2)	Is		_	_	-16	Α
Reverse Recovery Time	t _{rr}	T. 0500 L 101	_	24	_	nS
Reverse Recovery Charge	Qm	TJ=25°C, IF=-10A di/dt=100A/µs (Note 2)	_	16	_	nC

Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, $t \le 10$ sec.
- ③ Pulse Test: Pulse Width ≤ 300 μ s, Duty Cycle ≤ 2%.
- 4 Guaranteed by design, not subject to production
- \bigcirc Eas condition: Tj=25 $^{\circ}$ C,VDD=-10V,VG=-10V,L=0.5mH,Rg=25 Ω



Typical Electrical and Thermal Characteristics

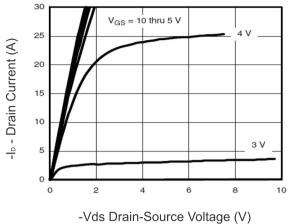
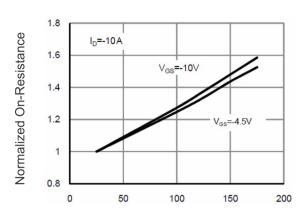


Figure 1 Output Characteristics



 $\label{eq:TJ-Junction} \mbox{Tu-Junction Temperature}(^{\circ}\mbox{C})$ Figure 4 Rdson-Junction Temperature

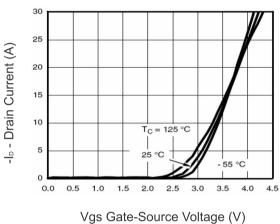
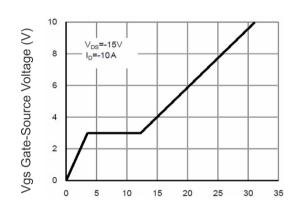


Figure 2 Transfer Characteristics



Qg Gate Charge (nC)
Figure 5 Gate Charge

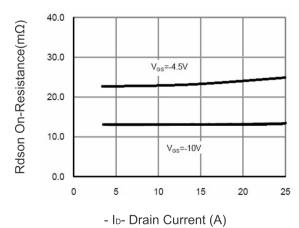


Figure 3 Rdson- Drain Current

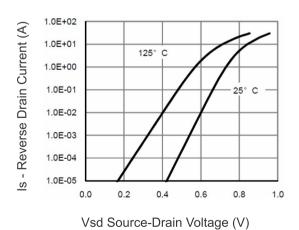


Figure 6 Source- Drain Diode Forward



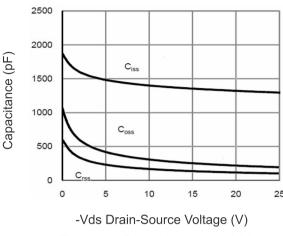
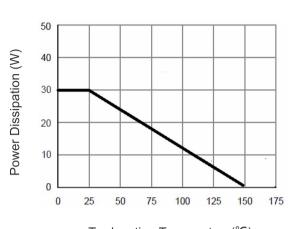


Figure 7 Capacitance vs Vds



T_J -Junction Temperature(°C) Figure 9 Power De-rating

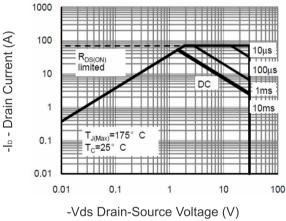
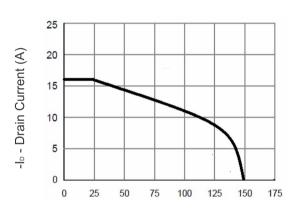
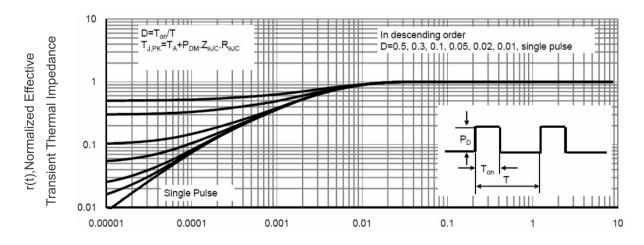


Figure 8 Safe Operation Area



T_J -Junction Temperature(°C)
Figure 10 -Current De-rating



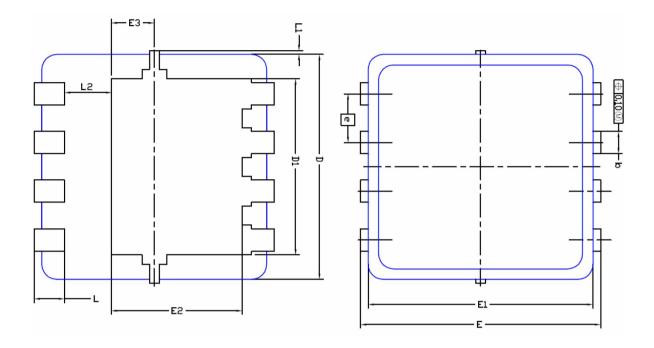
Square Wave Pluse Duration(sec)

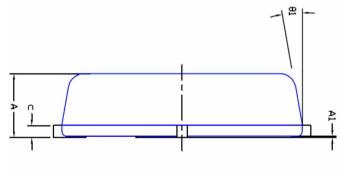
Figure 11 Normalized Maximum Transient Thermal Impedance





DFN3X3 EP Package Information





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DIM.	MILLIMETERS			INCHES			
DIN	MIN	NDM	MAX	MIN	NDM	MAX	
Α	0.700	0.80	0.900	0.0276	0.0315	0.0354	
A1	0.00		0.05	0.000		0.002	
b	0,24	0'30	0,35	0,009	0.012	0.014	
С	0,10	0,152	0,25	0,004	0,006	0,010	
D	3.00 BSC			0	.118 BS	C	
D1	2.35 BSC			0.093 BSC			
Ε	3.20 BSC			0.126 BSC			
E1	3,00 BSC			0.118 BSC			
E2	1.75 BSC			0.069 BSC			
E3	0.575 BSC			0.023 BSC			
е	0.65 BSC			0.026 BSC			
L2	0.685BSC			0.	0274BS	SC	
L	0.30	0.40	0.50	0.0118	0.0157	0.0197	
L1	0		0.100	0		0.004	
91	0°	10°	12°	0°	10°	12*	





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